

SOD-123FL Plastic-Encapsulate Diodes

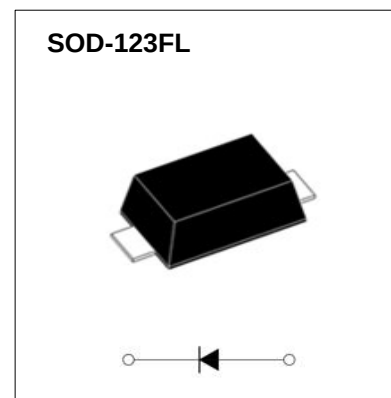
Fast Recovery Rectifier

Features

- I_O 1A
- VRRM 50V-1000V
- Low forward voltage drop
- High surge current capability
- Glass passivated chip junction

Mechical Data

- Case: SOD-123FL molded plastic
- Molding compound: UL flammability classification rating 94V-0
- Terminals: Solder plated, solderable per MIL- STD-202, Method 208
- Polarity: Color band denotes cathode end



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	FFM						
				101-M	102-M	103-M	104-M	105-M	106-M	107-M
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V_{DC}	V		50	100	200	400	600	800	1000
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, $T_L=100^{\circ}C$	1						
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, $T_a=25^{\circ}C$	30						
Junction Temperature	T_J	$^{\circ}C$		-55~+150						
Storage Temperature	T_{STG}	$^{\circ}C$		-55 ~ +150						

Electrical Characteristics ($T_a=25^{\circ}C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		FFM						
					101-M	102-M	103-M	104-M	105-M	106-M	107-M
Forward voltage	V _F	V	I _F =1.0A		1,3						
Maximum reverse recovery time	T _{rr}	ns	I _F =0.5A,I _R =1.0A,I _{rr} =0.25A		150			250	500		
Peak Reverse Current	I _{RRM1}	μA	V _{RM} =V _{RRM}	T _a =25°C	5						
	T _a =125°C			50							
Thermal Resistance(Typical)	R _{θJ-A}	°C/W	Between junction and ambient		85						
	R _{θJ-L}		Between junction and terminal		23						
	R _{θJ-C}		Between junction and case		15						
Juction Capacitance (Typical)	C _J	pF	Measured at 1.0MHz and applied reverse voltage of 4.0 volts.		6						

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

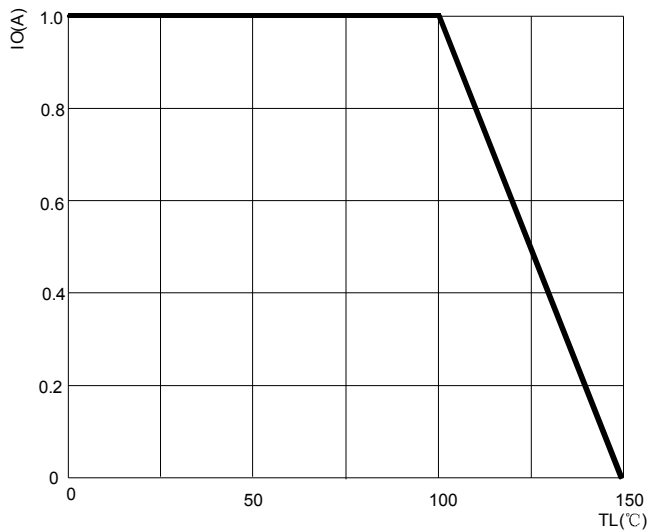


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

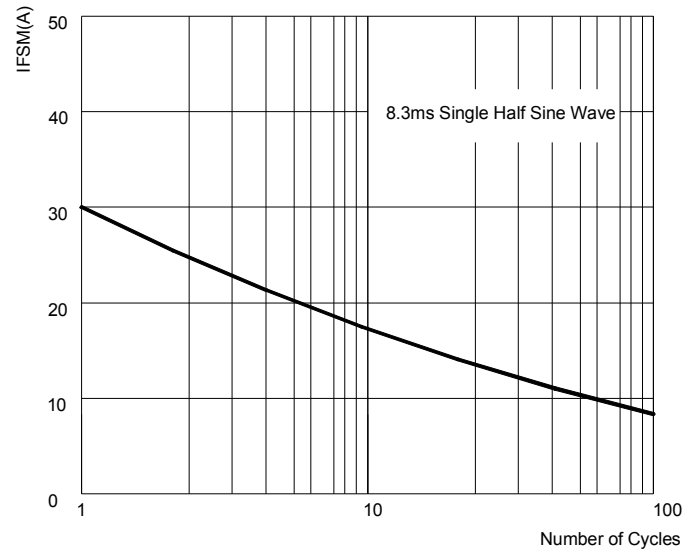


FIG.3: TYPICAL FORWARD CHARACTERISTICS

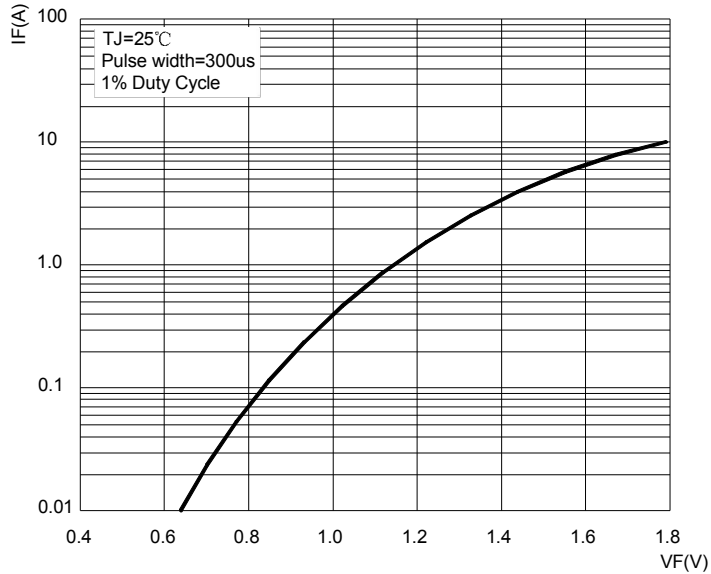


FIG.4: TYPICAL REVERSE CHARACTERISTICS

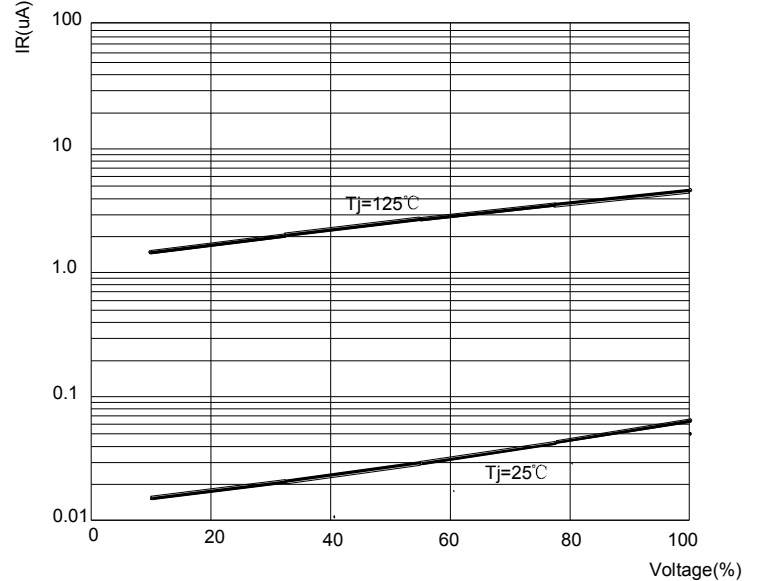
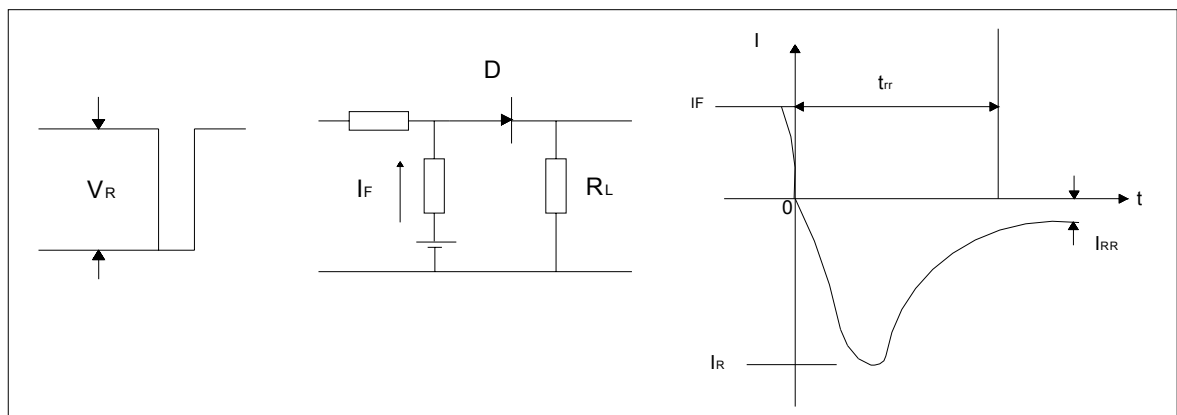
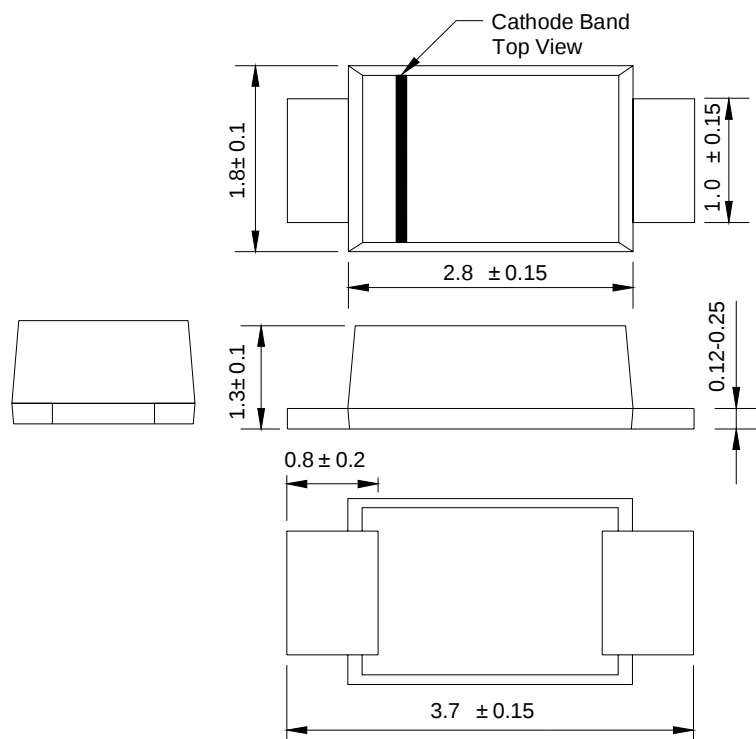


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

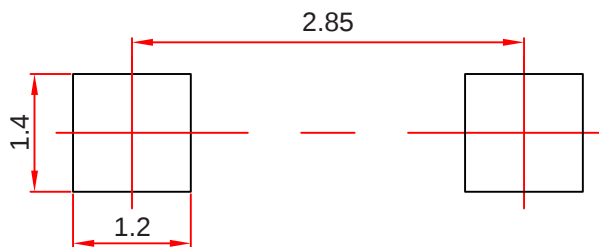


SOD-123FL Package Outline Dimensions



Dimensions in millimeters

SOD-123FL Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

Ordering Information

Part Number	Package	Shipping Quantity
FFM101-M -FFM107-M	SOD-123FL	3000/tape&Reel

Marking Diagram



FFM101-M - FFM104-M : F2
FFM105-M : F5
FFM106-M - FFM107-M : F7

Reel Taping Specifications For Surface Mount Devices–SOD-123FL

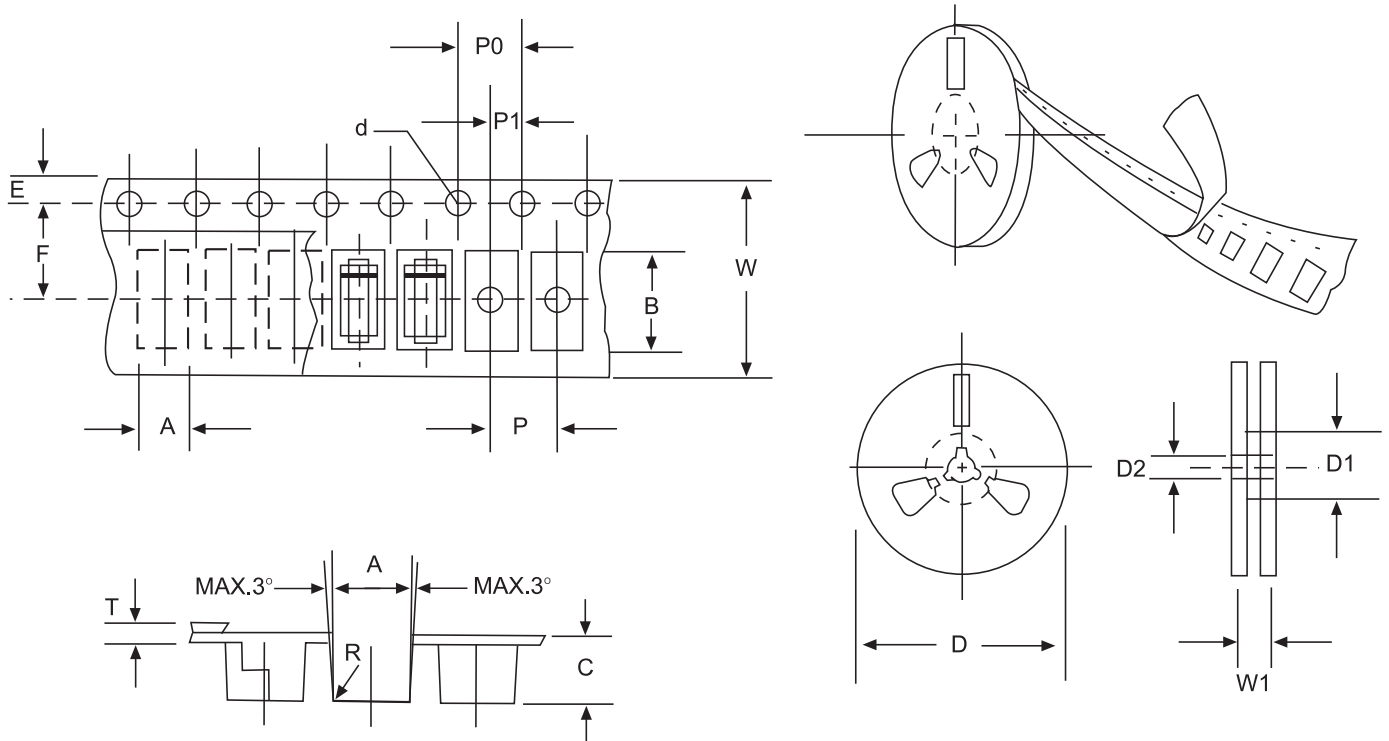


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SOD-123FLmm(inch)
Carrier width	A	2.05±0.1(0.081±0.004)
Carrier length	B	3.95±0.1(0.156±0.004)
Carrier depth	C	1.45±0.1(0.057±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	178±2.0(7.0±0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	3.50±0.1(0.138±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.21±0.25(0.008±0.010)
Tape width	W	8.0±0.2(0.315±0.008)
Reel width	W1	10.0±2.0(0.394±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.